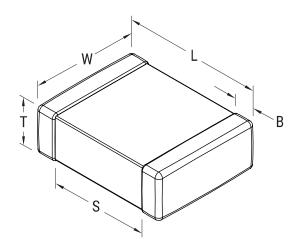


C0603C331J2TAC7411

SMD Comm X8G HT150C, Ceramic, 330 pF, 5%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.5 mm



Click here for the 3D model.

General Information Series SMD Comm X8G HT150C Style SMD Chip Description SMD, MLCC, High Temperature, Ultra-Stable Features High Temperature, Ultra-Stable RoHS Yes Termination Tin Marking No AEC-Q200 No **Typical Component Weight** 3.7 mg Shelf Life 78 Weeks MSL 1

	Specifications	
	Capacitance	330 pF
	Measurement Condition	1 MHz 1.0Vrms
	Tolerance	5%
	Voltage DC	200 VDC
	Dielectric Withstanding Voltage	500 VDC
	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
	Dissipation Factor	0.1% 1 MHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
	Insulation Resistance	100 GOhms

 Dimensions

 Chip Size
 0603

 L
 1.6mm +/-0.15mm

 W
 0.8mm +/-0.15mm

 T
 0.8mm +/-0.07mm

 S
 0.5mm MIN

 B
 0.35mm +/-0.15mm

Packaging Specifications Packaging

Packaging Quantity

T&R, 330mm, Paper Tape 15000

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